

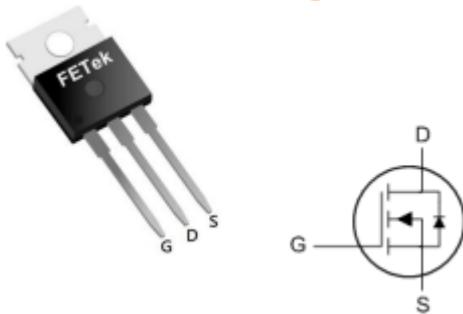
Description

The ECP0048 is the high cell density trench N-Ch MOSFETS, which provide excellent RDSON and gate charge for most of the Synchronous Rectification for AC/DC Quick Charger.

Product Summary

| | | |
|-------|-------|-----|
| BVDSS | RDSON | ID |
| 100V | 9mΩ | 80A |

TO220 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|------------------------|--|------------|-------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | ±20 | V |
| $I_D@T_C=25^{\circ}C$ | Continuous Drain Current ^{1,6} | 80 | A |
| $I_D@T_C=100^{\circ}C$ | Continuous Drain Current ^{1,6} | 70.7 | A |
| I_{DM} | Pulsed Drain Current ² | 350 | A |
| EAS | Single Pulse Avalanche Energy ³ | 61 | mJ |
| I_{AS} | Avalanche Current | 35 | A |
| $P_D@T_C=25^{\circ}C$ | Total Power Dissipation ⁴ | 188 | W |
| T_{STG} | Storage Temperature Range | -55 to 175 | °C |
| T_J | Operating Junction Temperature Range | -55 to 175 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient ¹ | --- | 58 | °C/W |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case ¹ | --- | 0.8 | °C/W |

**Electrical Characteristics** (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|---------------------|--|--|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 100 | --- | --- | V |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =10V, I _D =13.5A | --- | 6.6 | 9 | mΩ |
| | Static Drain-Source On-Resistance ² | V _{GS} =4.5V, I _D =11.5A | --- | 8.7 | 12 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 1.2 | --- | 2.3 | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =80V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =80V, V _{GS} =0V, T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±20V, V _{DS} =0V | --- | --- | ±100 | nA |
| g _{fs} | Forward Transconductance | V _{DS} =5V, I _D =20A | --- | 85 | --- | S |
| Q _g | Total Gate Charge (10V) | V _{DS} =50V, V _{GS} =10V, I _D =13.5A | --- | 45 | --- | nC |
| Q _g | Total Gate Charge (4.5V) | | --- | 19.3 | --- | |
| Q _{gs} | Gate-Source Charge | | --- | 9.5 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 4.8 | --- | |
| T _{d(on)} | Turn-On Delay Time | | --- | 10 | --- | |
| T _r | Rise Time | V _{DD} =50V, V _{GS} =10V, R _G =3Ω, I _D =13.5A | --- | 6.5 | --- | ns |
| T _{d(off)} | Turn-Off Delay Time | | --- | 45 | --- | |
| T _f | Fall Time | | --- | 7.5 | --- | |
| C _{iss} | Input Capacitance | | --- | 3320 | --- | |
| C _{oss} | Output Capacitance | V _{DS} =50V, V _{GS} =0V, f=1MHz | --- | 605 | --- | pF |
| C _{rss} | Reverse Transfer Capacitance | | --- | 20 | --- | |

Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|---|------|------|------|------|
| I _S | Continuous Source Current ^{1,5,6} | V _G =V _D =0V, Force Current | --- | --- | 80 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1.1 | V |
| t _{rr} | Reverse Recovery Time | I _F =13.5A, di/dt=100A/μs, | --- | 33 | --- | nS |
| Q _{rr} | Reverse Recovery Charge | T _J =25°C | --- | 150 | --- | |

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.3mH, I_{AS}=35A
- 4.The power dissipation is limited by junction temperature
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.
- 6.The maximum current rating is package limited.

Typical Characteristics

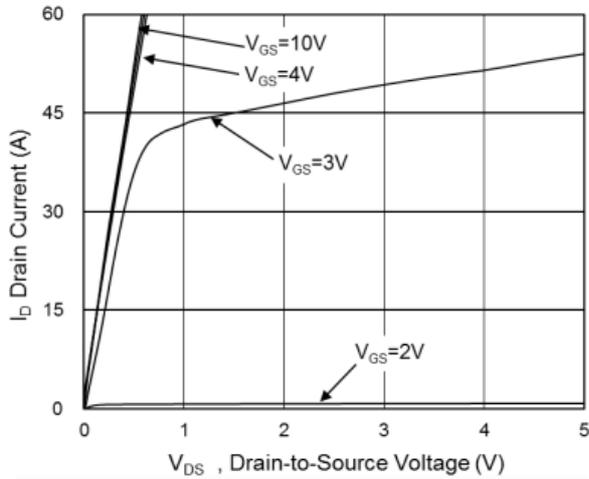


Fig.1 Typical Output Characteristics

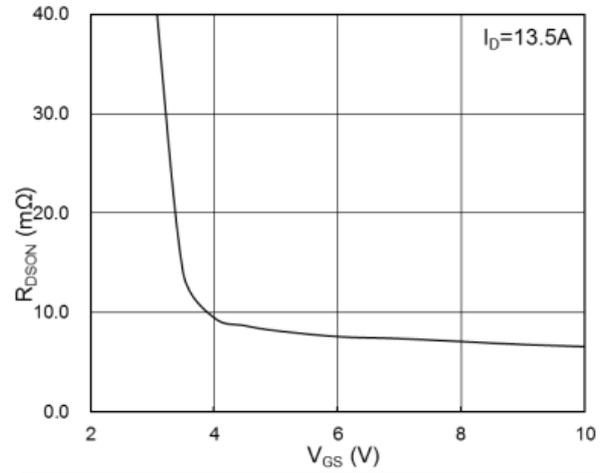


Fig.2 On-Resistance vs. G-S Voltage

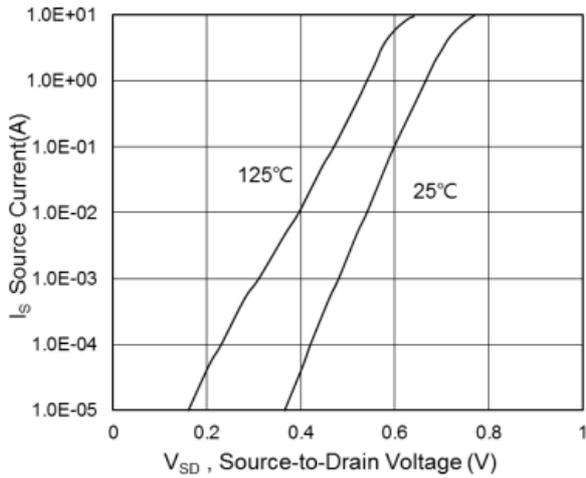


Fig.3 Source-Drain Forward Characteristics

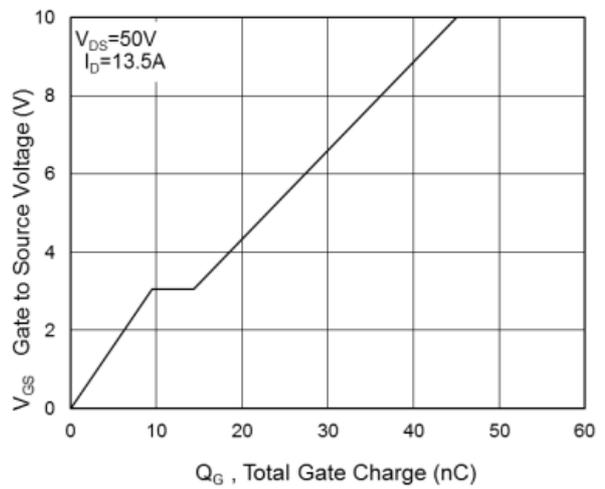


Fig.4 Gate-Charge Characteristics

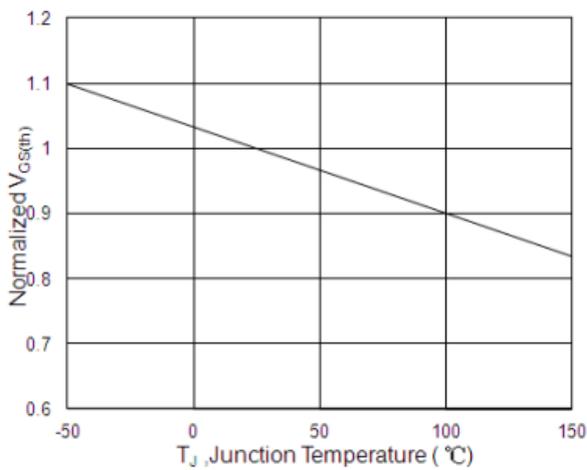


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

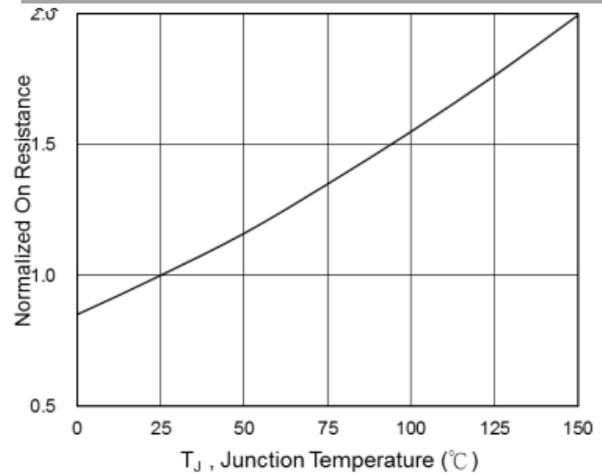


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

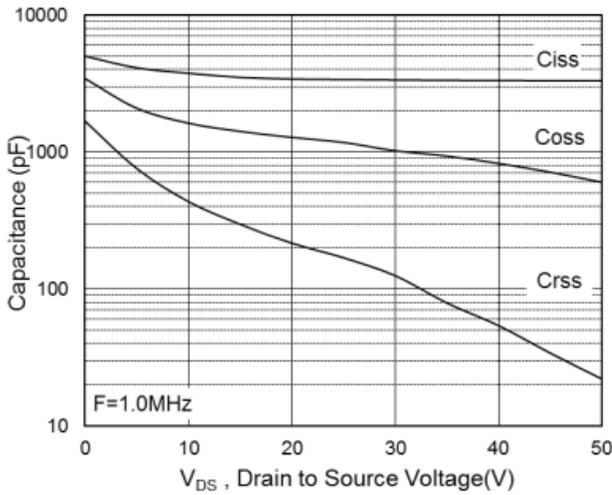


Fig.7 Capacitance

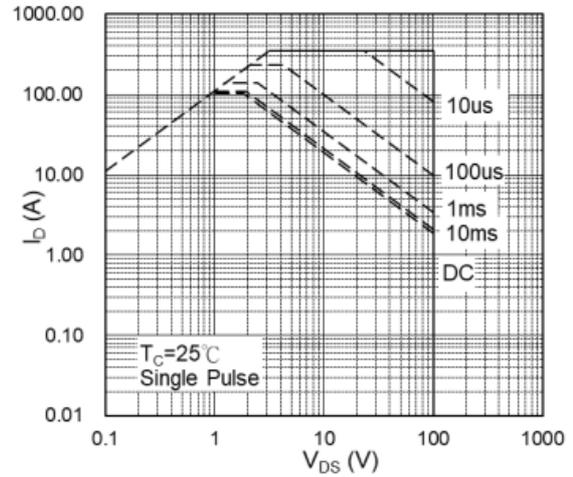


Fig.8 Safe Operating Area

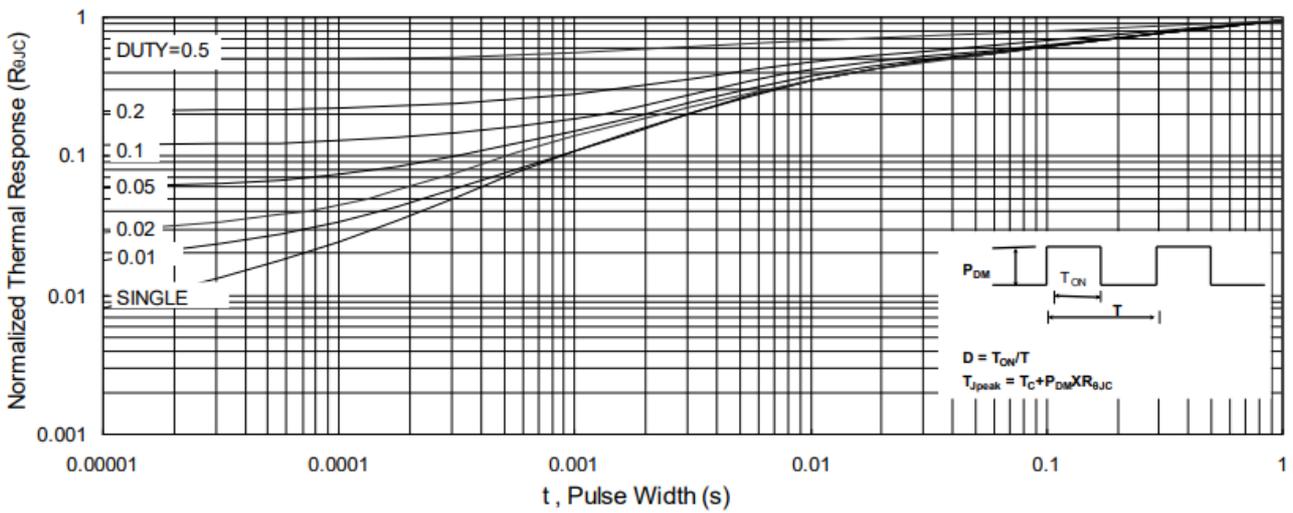


Fig.9 Normalized Maximum Transient Thermal Impedance

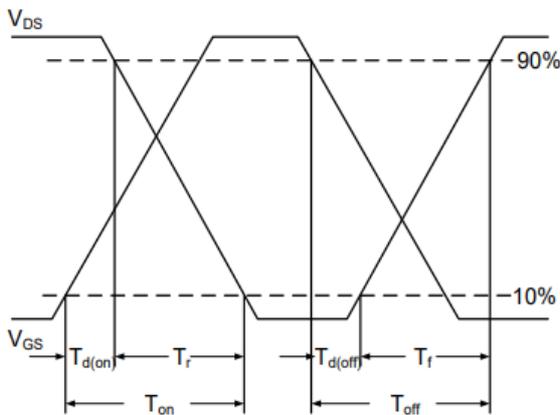


Fig.10 Switching Time Waveform

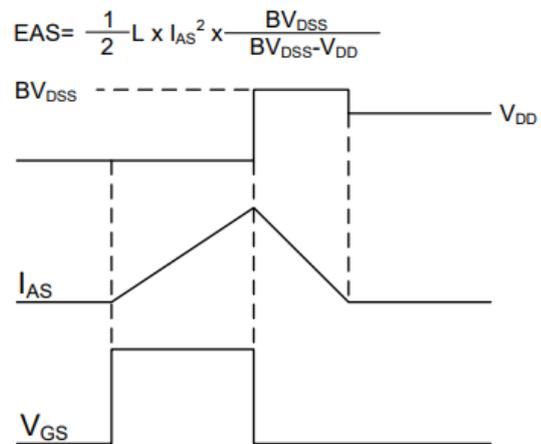
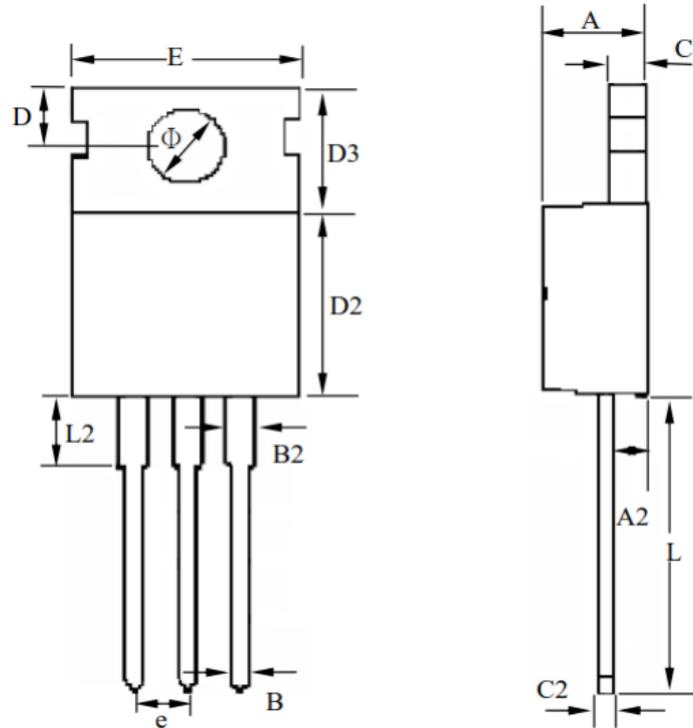


Fig.11 Unclamped Inductive Switching Waveform

TO220 Package Outline Dimensions



| SYMBOLS | MILLIMETERS | | | INCHES | | |
|---------|-------------|------|-------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 4.25 | -- | 4.80 | 0.167 | -- | 0.189 |
| A2 | 2.20 | -- | 2.92 | 0.087 | -- | 0.115 |
| B | 0.70 | -- | 0.91 | 0.028 | -- | 0.036 |
| B2 | 1.15 | -- | 1.77 | 0.045 | -- | 0.070 |
| C | 1.20 | -- | 1.40 | 0.047 | -- | 0.055 |
| C2 | 0.45 | -- | 0.61 | 0.018 | -- | 0.024 |
| D | 2.54 | -- | 3.00 | 0.100 | -- | 0.118 |
| D2 | 8.39 | -- | 9.47 | 0.330 | -- | 0.373 |
| D3 | 6.30 | -- | 6.70 | 0.248 | -- | 0.264 |
| E | 9.70 | -- | 10.36 | 0.382 | -- | 0.408 |
| L | 12.75 | -- | 14.40 | 0.502 | -- | 0.567 |
| L2 | 2.45 | -- | 4.05 | 0.096 | -- | 0.159 |
| Φ | 3.50 | -- | 3.80 | 0.138 | -- | 0.150 |
| e | -- | 2.54 | -- | -- | 0.100 | -- |